1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			100	V
$I_{F(RMS)}$	Forward rms current			10	A
$I_{F(AV)}$	Average forward current, δ = 0.5	SMA	T_L = 150 °C	1	A
		SMB, SMA Flat	T_L = 155 °C		
		SMA Flat Notch	T_L = 160 °C		
I_{FSM}	Surge non repetitive forward current		t_p = 10 ms sinusoidal	50	A
P_{ARM}	Repetitive peak avalanche power		t_p = 10 µs, T_j = 125 °C	108	W
T_{stg}	Storage temperature range			-65 to +175	°C
T_j	Maximum operating junction temperature(1)			+175	°C

1. *$(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.*

Table 2. Thermal parameters

Symbol	Parameter		Max. value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30	°C/W
		SMB	25	
		SMA Flat, SMA Flat Notch	20	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I_R(1)	Reverse leakage current	T_j = 25 °C	$V_R = V_{RRM}$	-		4	µA
		T_j = 125 °C		-	0.2	0.5	mA
V_F(2)	Forward voltage drop	T_j = 25 °C	I_F = 1 A	-		0.77	V
		T_j = 125 °C		-	0.58	0.62	
		T_j = 25 °C	I_F = 2 A	-		0.86	
		T_j = 125 °C		-	0.65	0.70	

1. *Pulse test: tp = 5 ms, δ < 2%*
2. *Pulse test: t_p = 380 µs, δ < 2%*

To evaluate the conduction losses, use the following equation:

$P = 0.54 \times I_{F(AV)} + 0.08 \times I_F{}^2{}_{(RMS)}$

1.1 Characteristics (curves)

Figure 1. Average forward power dissipation versus average forward current

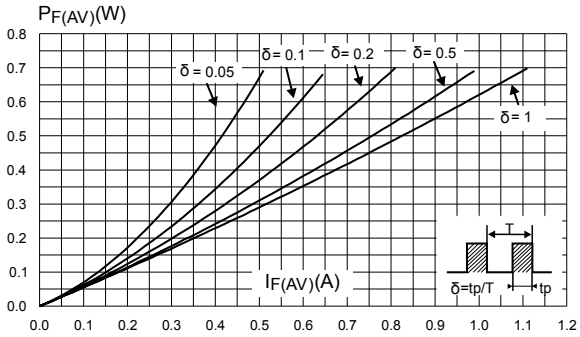


Figure 2. Average forward current versus ambient temperature (δ = 0.5)

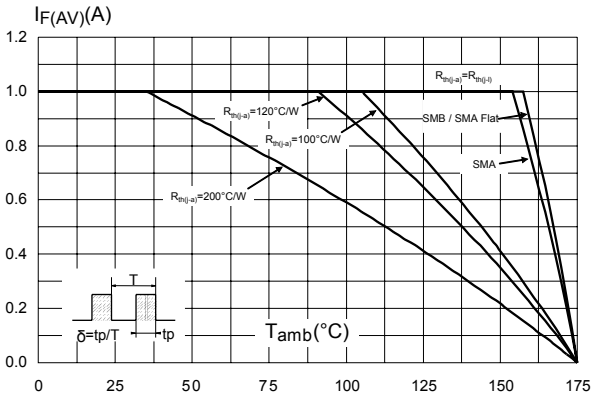


Figure 3. Normalized avalanche power derating versus junction temperature (T_j = 125 °C)

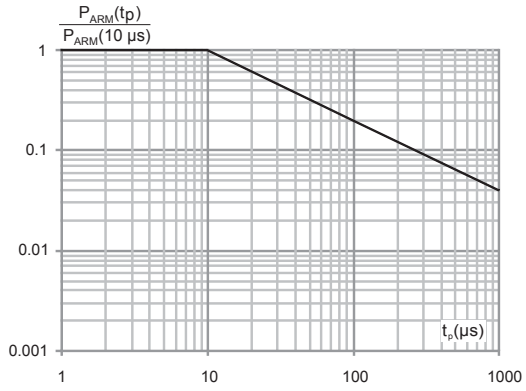


Figure 4. Junction capacitance versus reverse voltage applied (maximum values)

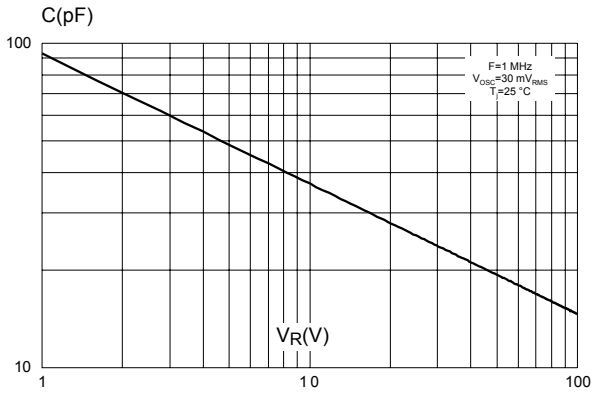


Figure 5. Relative variation of thermal impedance junction to ambient versus pulse duration

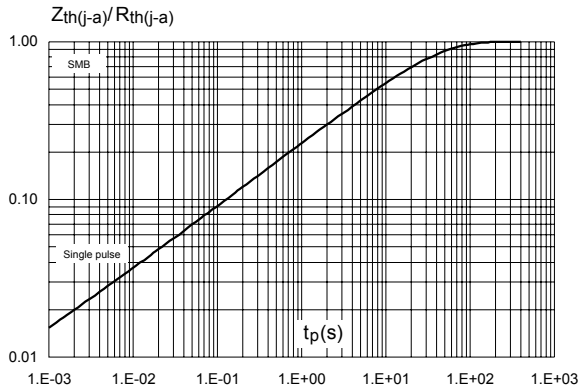


Figure 6. Relative variation of thermal impedance junction to ambient versus pulse duration

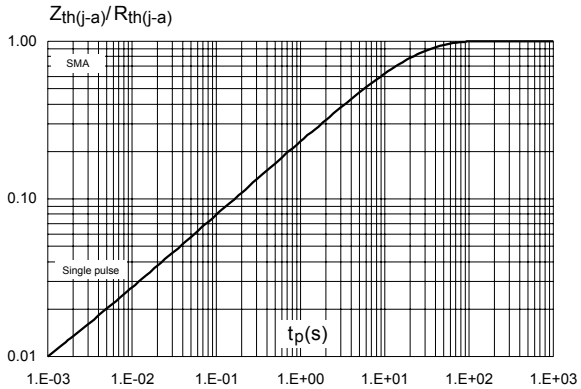


Figure 7. Relative variation of thermal impedance junction to ambient versus pulse duration

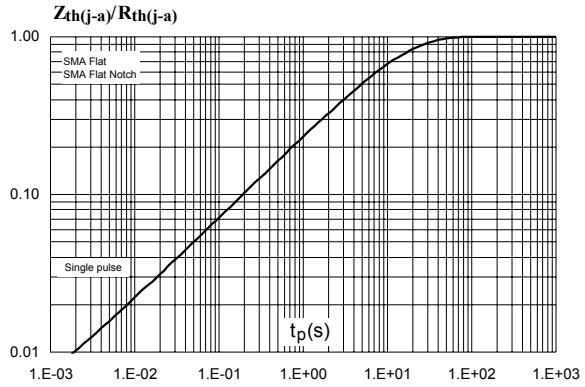


Figure 8. Reverse leakage current versus reverse voltage applied (typical values)

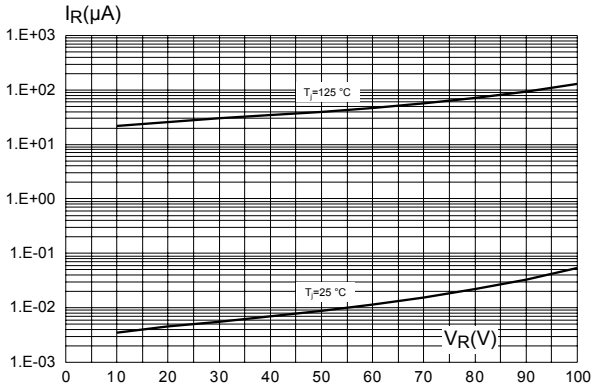


Figure 9. Forward voltage drop versus forward current (maximum values)

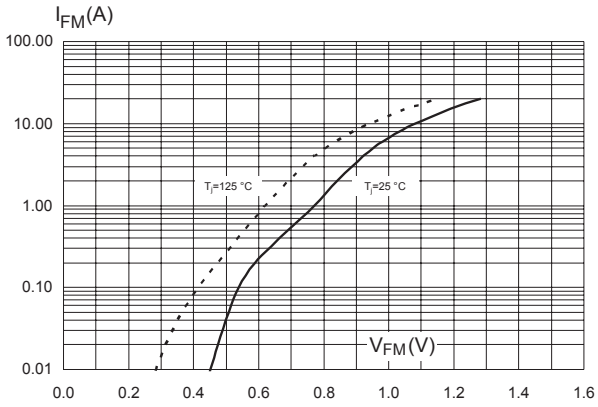


Figure 10. Thermal resistance junction to ambient versus copper surface under each lead (SMB)

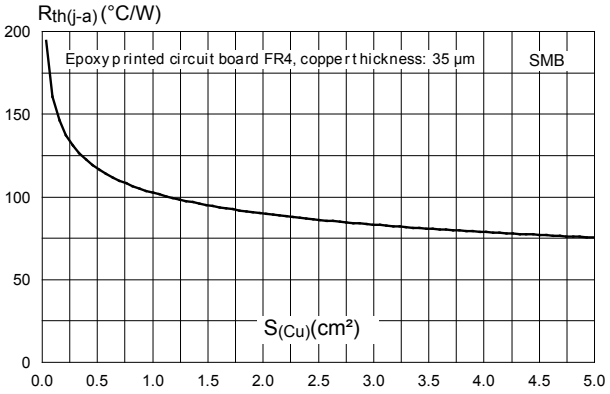


Figure 11. Thermal resistance junction to ambient versus copper surface under each lead

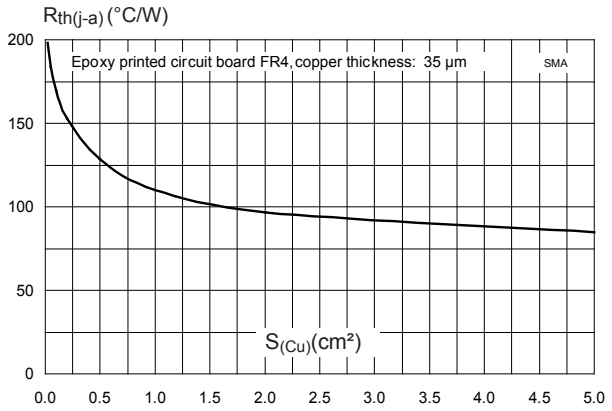
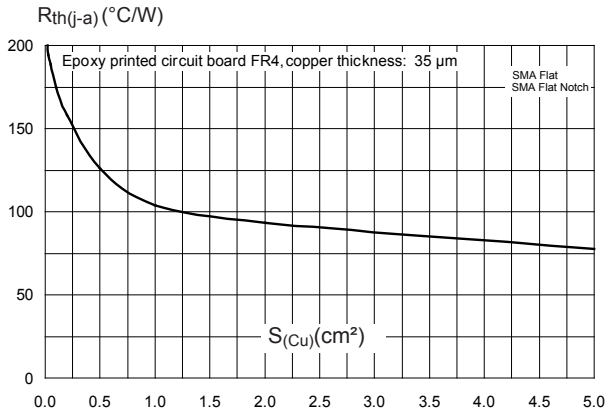


Figure 12. Thermal resistance junction to ambient versus copper surface under each lead



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

2.1 SMB package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 13. SMB package outline

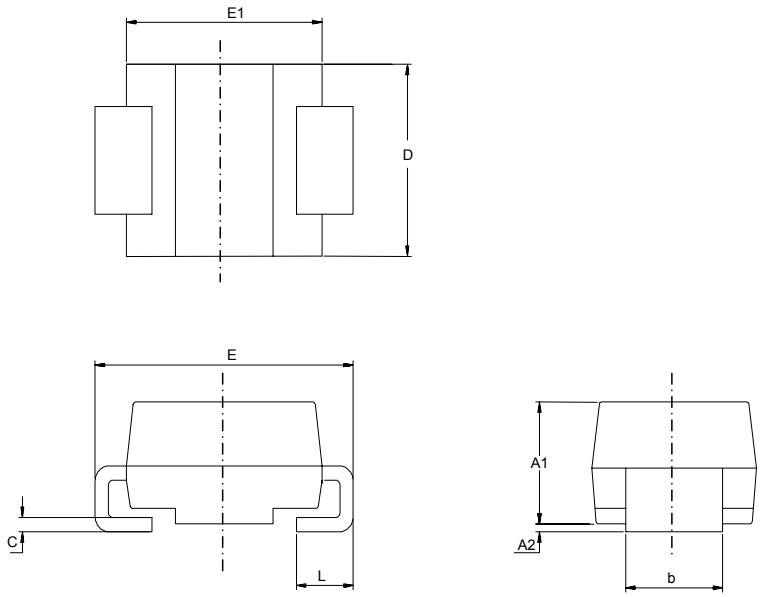
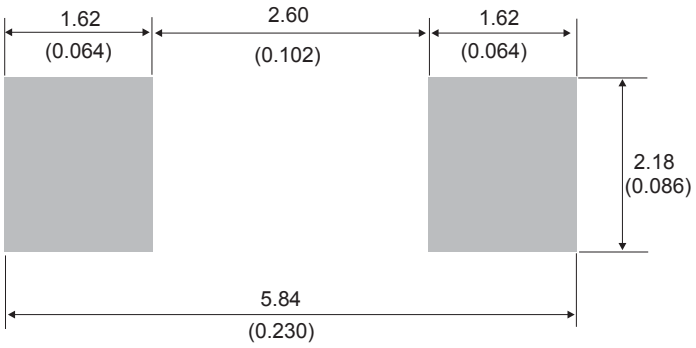


Table 4. **SMB package mechanical data**

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.0748	0.0965
A2	0.05	0.20	0.0020	0.0079
b	1.95	2.20	0.0768	0.0867
c	0.15	0.40	0.0059	0.0157
D	3.30	3.95	0.1299	0.1556
E	5.10	5.60	0.2008	0.2205
E1	4.05	4.60	0.1594	0.1811
L	0.75	1.50	0.0295	0.0591

Figure 14. **SMB recommended footprint**



2.2 SMA package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 15. SMA package outline

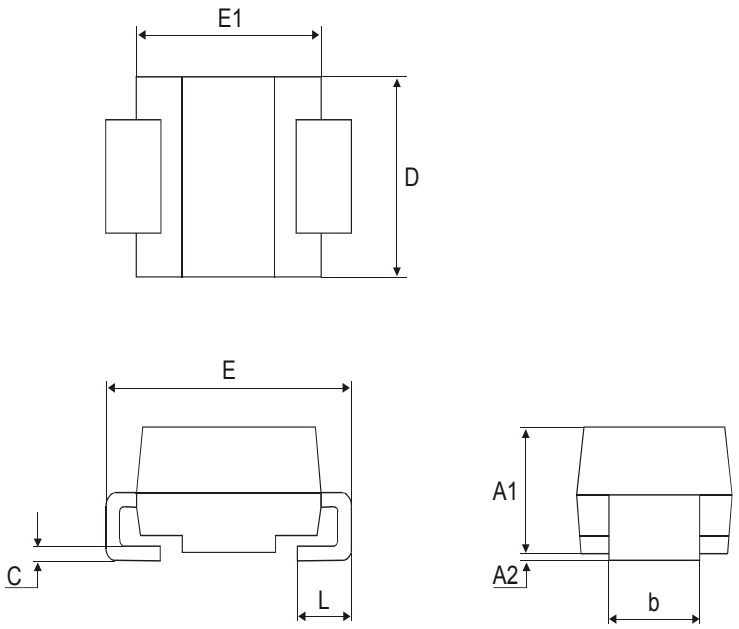
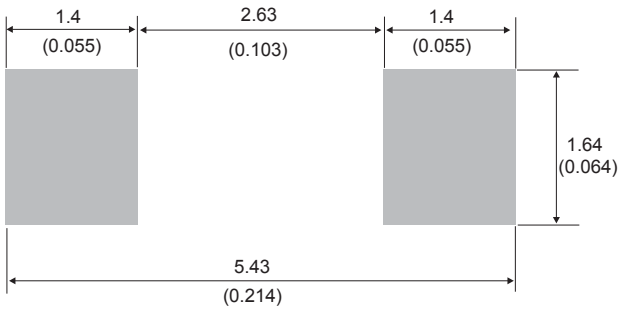


Table 5. SMA package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.097
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.006	0.016
D	2.25	2.90	0.089	0.114
E	4.80	5.35	0.189	0.211
E1	3.95	4.60	0.156	0.181
L	0.75	1.50	0.030	0.059

Figure 16. **SMA recommended footprint in mm (inches)**



2.3 SMA Flat package information

- Epoxy meets UL94, V0
- Lead-free package

Figure 17. SMA Flat package outline

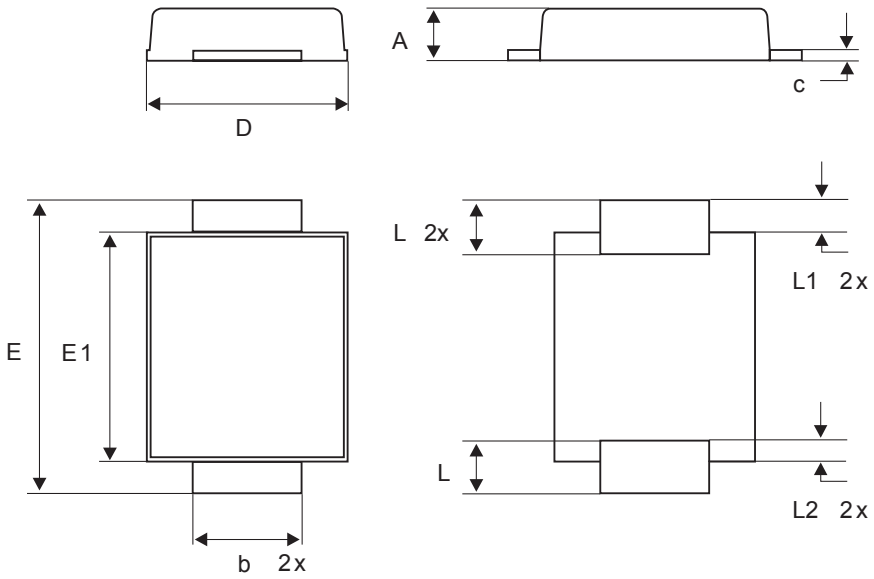
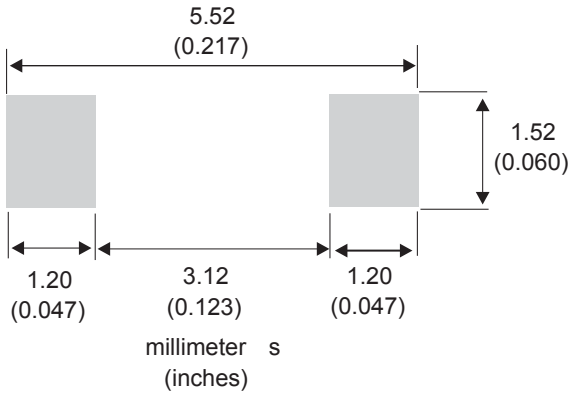


Table 6. SMA Flat package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.90		1.10	0.035		0.044
b	1.25		1.65	0.049		0.065
c	0.15		0.40	0.005		0.016
D	2.25		2.95	0.088		0.117
E	4.80		5.60	0.188		0.221
E1	3.95		4.60	0.155		0.182
L	0.75		1.50	0.029		0.060
L1		0.50			0.020	
L2		0.50			0.020	

Figure 18. **SMA Flat recommended footprint in mm (inches)**



2.4 SMA Flat Notch package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Band indicates cathode

Figure 19. SMA Flat Notch package outline

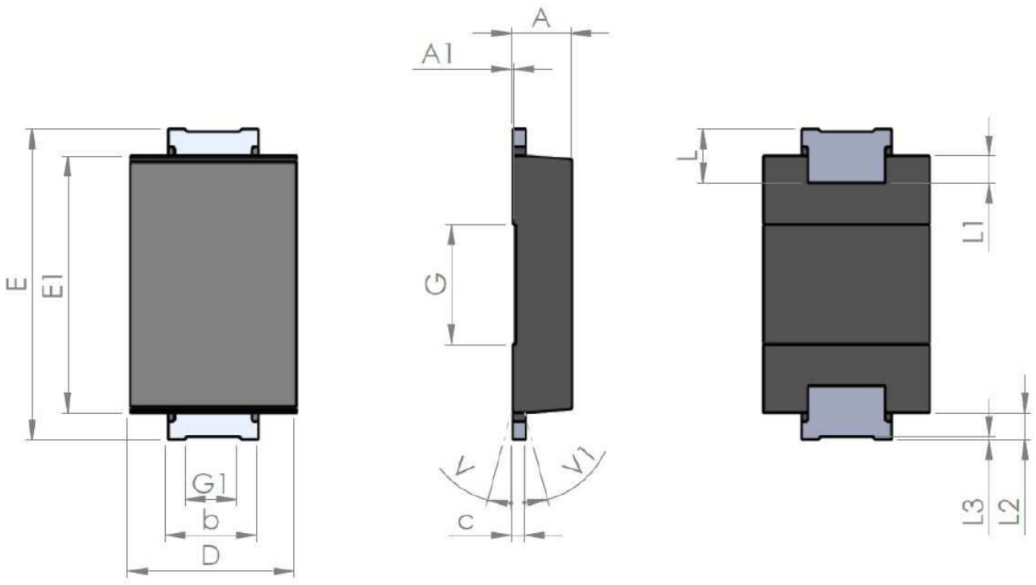
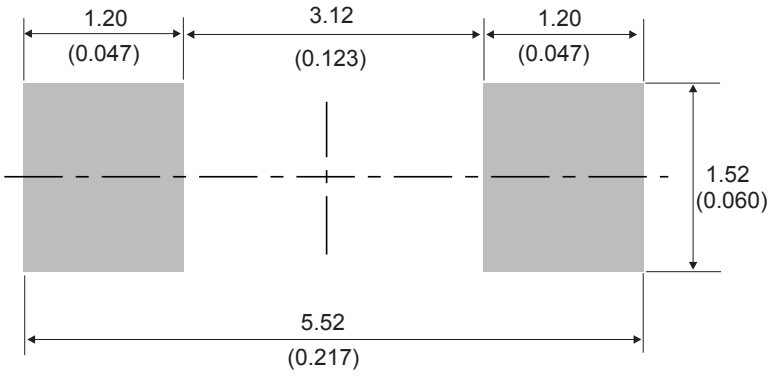


Table 7. SMA Flat Notch package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A1	0.90		1.10	0.035		0.044
A1		0.05			0.002	
b	1.25		1.65	0.049		0.065
C	0.15		0.40	0.005		0.016
D	2.25		2.90	0.088		0.115
E	5.00		5.35	0.196		0.211
E1	3.95		4.60	0.155		0.182
G		2.00			0.079	
G1		0.85			0.033	
L	0.75		1.20	0.029		
L1		0.45			0.018	
L2		0.45			0.018	
L3		0.05			0.002	
V			8°			8°
V1			8°			8°

Figure 20. **SMA Flat Notch recommended footprint in mm (inches)**



3 Ordering Information

Table 8. **Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS1H100A	S11	SMA	0.068 g	5000	Tape and reel
STPS1H100U	G11	SMB	0.107 g	2500	Tape and reel
STPS1H100AF	F11	SMA Flat	0.035 g	10 000	Tape and reel
STPS1H100AFN	A11	SMA Flat Notch	0.039 g	10 000	Tape and reel

Revision history

Table 9. Document revision history

Date	Version	Changes
Jul-2003	4A	Last update.
Aug-2004	5	SMA package dimensions update. Reference A1 max changed from 2.70 mm (0.106 inc.) to 2.03 mm (0.080 inc).
18-Sep-2008	6	Reformatted to current standards. Added SMAflat package.
06-Apr-2018	7	Updated Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified), Figure 3. Normalized avalanche power derating versus junction temperature (T_j = 125 °C). Removed "Normalized avalanche power derating versus junction temperature".
08-Oct-2019	8	Added Section 2.4 SMA Flat Notch package information.